

ForTii[®] Eco LDS62B

PA*—GF35

35% Glass Fiber Reinforced, Laser Direct Structuring (LDS), Low Warpage

Print Date: 2025-08-21

ForTii[®] Eco LDS62B is a high ductility LDS material which enables good structural integrity in complicated geometries. It is well suited for wearable devices and smart phone antennas for consumer electronics. It has excellent dimensional stability to ensure low warpage after chemical plating. Eco LDS62B is Eco-friendly due to its partly bio-based content.

Sustainability

Bio-based

PROPERTIES	TYPICAL DATA	UNIT	TEST METHOD
RHEOLOGICAL PROPERTIES		DRY / COND	
Molding shrinkage (parallel)	0.21 / *	%	ISO 294-4
Molding shrinkage (normal)	0.7 / *	%	ISO 294-4
MECHANICAL PROPERTIES		DRY / COND	
Tensile modulus	11500 / -	MPa	ISO 527-1/-2
Stress at break	130 / -	MPa	ISO 527-1/-2
Strain at break	1.7 / -	%	ISO 527-1/-2
Flexural modulus	10000 / -	MPa	ISO 178
Flexural strength	190 / -	MPa	ISO 178
Charpy notched impact strength (+23°C)	4.6 / -	kJ/m²	ISO 179/1eA
THERMAL PROPERTIES		DRY / COND	
Melting temperature (10°C/min)	319 / *	°C	ISO 11357-1/-3
Temp. of deflection under load (1.80 MPa)	235 / *	°C	ISO 75-1/-2
Coeff. of linear therm. expansion (parallel)	0.17 / *	E-4/°C	ISO 11359-1/-2
Coeff. of linear therm. expansion (normal)	0.66 / *	E-4/°C	ISO 11359-1/-2

Seller represents and warrants exclusively that on the date of delivery by Seller the product shall be in conformity with the specifications agreed upon. Seller makes no other representations or warranties, whether express or implied.
Seller is not responsible or liable for the design of the products of the Customer and it is the responsibility of the Customer to determine that the Seller's product is safe, complies with application laws and regulations, and is technically or otherwise fit for its intended use. Seller does not endorse or claim suitability of its products for a specific application and disclaims each and every representation or warranty, whether express or implied, in that respect.
Typical values are indicative only and are not to be construed as being binding specifications. Colorants in the product or other additives may cause significant variations in typical values.
Copyright © Envalior 2025. All rights reserved. No part of the information may be reproduced, distributed, or transmitted in any form or by any means, including photocopying, recording, or other electronic or mechanical methods, without the prior written permission of Envalior.

Property Data

ForTii[®] Eco LDS62B

Print Date: 2025-08-21

PROPERTIES	TYPICAL DATA	UNIT	TEST METHOD
Burning Behav. at 1.5 mm nom. thickn.	HB / *	class	IEC 60695-11-10
Thickness tested	1.5 / *	mm	IEC 60695-11-10
UL recognition	Yes / *	—	—
Burning Behav. at 3.0 mm nom. thickn.	HB / *	class	IEC 60695-11-10
Thickness tested	HB / *	mm	IEC 60695-11-10
UL recognition	3 / *	—	—
ELECTRICAL PROPERTIES		DRY / COND	
Relative permittivity (1GHz)	3.74 / 3.8	—	IEC 61189-2-721
OTHER PROPERTIES		DRY / COND	
Density	1500 / —	kg/m³	ISO 1183

Seller represents and warrants exclusively that on the date of delivery by Seller the product shall be in conformity with the specifications agreed upon. Seller makes no other representations or warranties, whether express or implied.
Seller is not responsible or liable for the design of the products of the Customer and it is the responsibility of the Customer to determine that the Seller's product is safe, complies with application laws and regulations, and is technically or otherwise fit for its intended use. Seller does not endorse or claim suitability of its products for a specific application and disclaims each and every representation or warranty, whether express or implied, in that respect.
Typical values are indicative only and are not to be construed as being binding specifications. Colorants in the product or other additives may cause significant variations in typical values.
Copyright © Envalior 2025. All rights reserved. No part of the information may be reproduced, distributed, or transmitted in any form or by any means, including photocopying, recording, or other electronic or mechanical methods, without the prior written permission of Envalior.